

Application No. 10/028,144

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph starting at p. 2, line 5 with the following:

This application is a continuation-in-part application of U.S. Patent Application Serial No. 09/895,350 entitled "Microminiature Thermionic Converters," to King, et al., filed on June 27, 2001, now US Patent 6,509,669, which issued 01/21/2003; U.S. Patent Application Serial No. 09/895,759 entitled "Thermionic Modules," to King, et al., filed on June 27, 2001, now US Patent 6,407,477, which issued 06/18/2002; U.S. Patent Application Serial No. 09/895,372 entitled "Chemical Vapor Deposition Techniques and Related Methods for Manufacturing Microminiature Thermionic Converters," to King, et al., filed on June 27, 2001, now US Patent 6,411,007, which issued 06/25/2001; and U.S. Patent Application Serial No. 09/257,336 entitled "Low Work Function Materials for Microminiature Energy Conversion and Recovery Applications," to Zavadil, Ruffner, and King, filed on February 25, 1999, now US Patent 6,563,256, which issued 05/13/2003. This application is related to U.S. Patent 6,294,858, "Microminiature Thermionic Converters", which issued 09/25/2001 to King et al., and to co-pending applications "Micro Heat Barrier", Serial No. 10/025,449 filed 12/19/2001 by Marshall et al., and "Methods for Fabricating a Micro Heat Barrier", Serial No. 10/025,718 filed 12/19/2001 by Marshall et al. The specifications thereof of all of the above are incorporated herein by reference.

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Please replace the paragraph starting at p. 4, line 3 with the following:

Reducing the spacing between electrodes to the order of microns has proved impractical with conventional manufacturing techniques. Fitzpatrick (U.S. Patent No. 4,667,126) teaches "maintenance of such small spacing with high temperatures and heat fluxes is a difficult if not impossible technical challenge." The present invention overcomes the difficulty of reducing spacing by microengineering. U.S. Patent 6,294,858 to King, et al., "Microminiature Thermionic Converters", which is hereby incorporated herein by reference, discloses a microminiature thermionic converter having a 1 micron electrode gap manufactured by integrated circuit (IC) semiconductor techniques. U.S. Patent ~~6,229,983~~ 6,299,083 to Edelson, "Thermionic Converter", also discloses a microminiature thermionic converter fabricated using MEMS techniques. Both King's device and Edelson's device are powered by an external source of heat; not by an internal, self-contained power source, as in the present invention.